

SL-T3510RGBA-L120 DATA SHEET

SPEC.NO.: DATE: REV. <u>SZ18040901</u> <u>2018/04/09</u> <u>A/0</u>

Approved By:

Checked By:

Prepared By:

	Part No./	SL-T3510RGBA-L120	Page	1 of 13
--	-----------	-------------------	------	---------

Rol





SL-T3510RGBA-L120

TOP Full-color LED

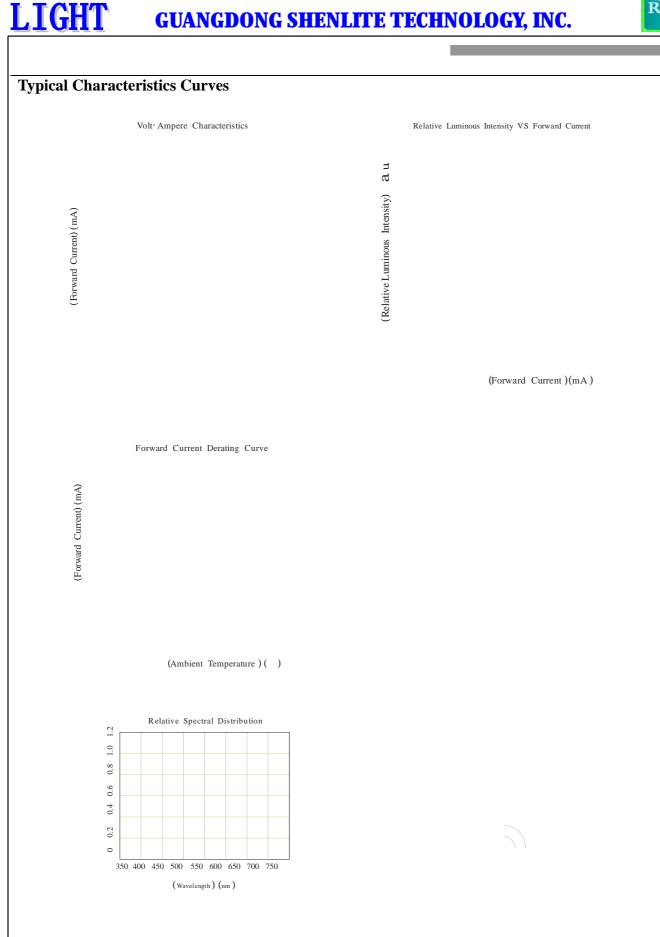
Technical Data Sheet

These products are full-color SMD component and designed for outdoor display with white refractor, high brightness,

Part No./	SL-T3510RGBA-L120	Page	2 of 13
-----------	-------------------	------	---------

LG-QR-R009-01





Part No./	SL-T3510RGBA-L120	Page	4 of 13

Reliability Test Items And Conditions

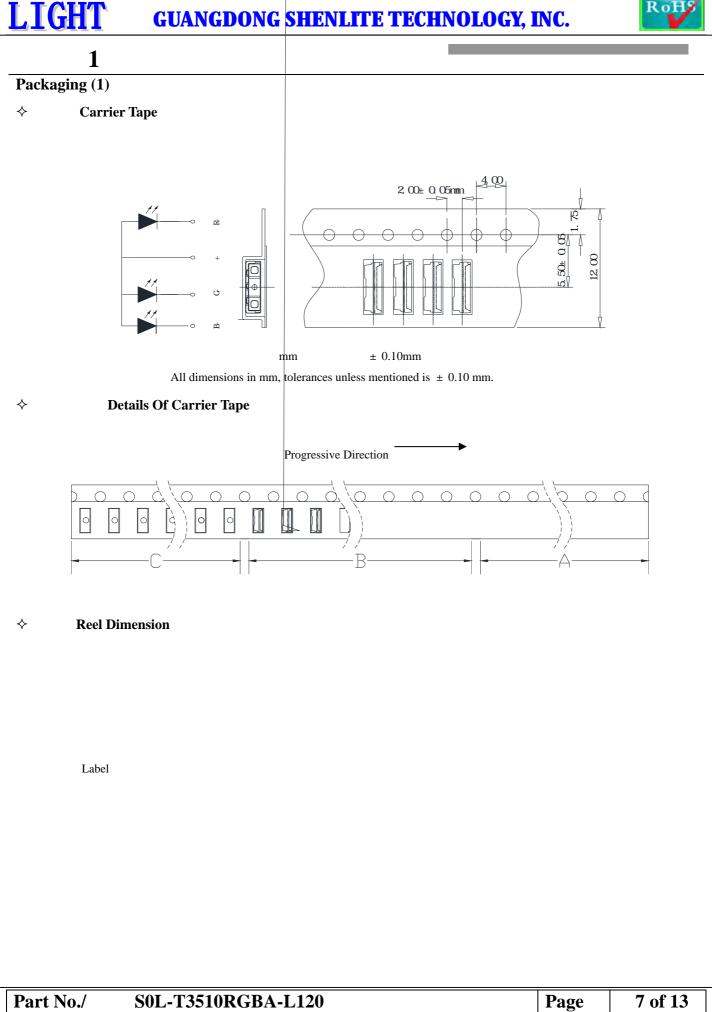
LIGHT

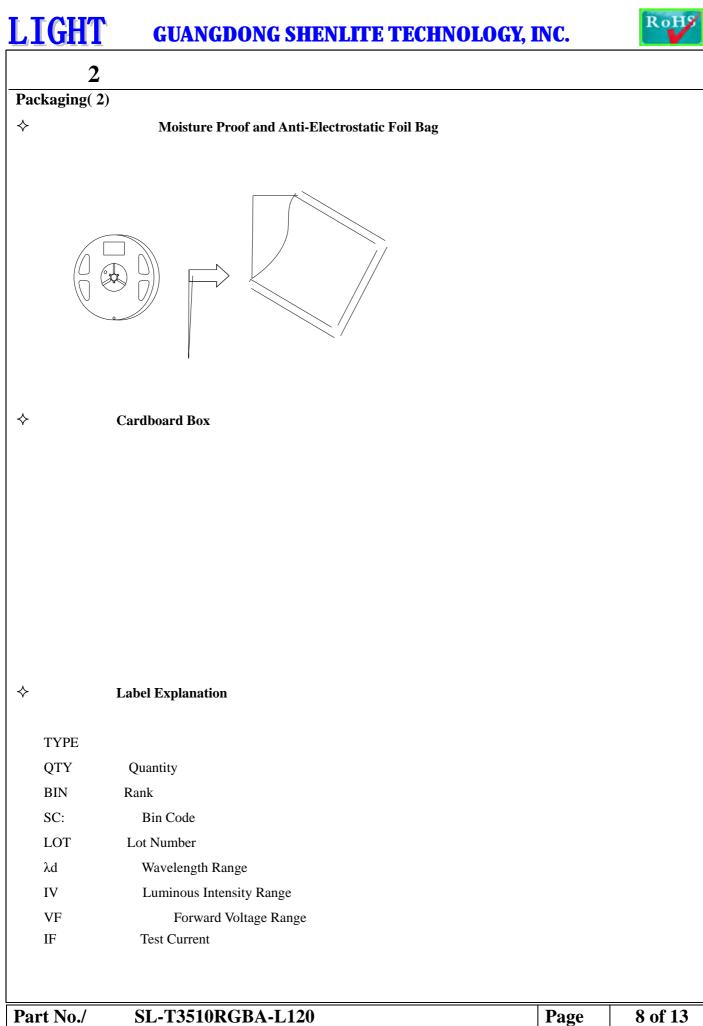
Test Items	Reference	Test Conditions	Time	Quantit	Crite
Thermal Shock	MIL-STD-202G	-40 (30min)←→100 (30min)	300 300 cycles	22	0/22
Temperature And Humidity Cyclic	JEITA ED-4701 200 203	-10+65 0%-90%RH 24hrs./1cycle	10 10 cycles	22	0/22
High Temperature Storage	JEITA ED-4701 200 201	Ta=100	1000h	22	0/22
Low Temperature Storage	JEITA ED-4701 200 202	Ta=-40	1000h	22	0/22
High Temperature High Humidity Storage	JEITA ED-4701 100 103	Ta=60 RH=90%	1000h	22	0/22
Life Test	JESD22-A108D	$Ta=25$ $IF_{R} = 15 mA, IF_{G} = 8 mA, IF_{B} = 5 mA$	1000h	22	0/22
High Temperature Life Test	JESD22-A108D	$Ta=85$ $IF_{R} = 15 mA, IF_{G} = 8 mA, IF_{B} = 5 mA$	1000h	22	0/22
Low Temperature Life Test	JESD22-A108D	$Ta=-40$ $IF_{R} = 15 \text{mA}, IF_{G} = 8 \text{mA}, IF_{B} = 5 \text{mA}$	1000h	22	0/22
Resistance to Soldering Heat	GB/T 4937, ,2.2&2.3	Tsol*=260 10sec.	2 2 times	22	0/22

Criteria For Judging Damage

	Test Items	Symbol 7	Fest Conditions	COOQtin F3(4)xBz 295.7D 70493	ē7.5% cs 0r28833	3Tw 10
P	Part No./ SL-7	T3510RGBA	-L120		Page	5 of 13	

LIGHT





LIGHT



LIGHT



2			
Guideline for Soldering (2)			
• Reflow soldering should not be done more than one time.			
· LED			
• Stress on the LEDs should be avoided during heating in the	he reflow soldering	process.	
		•	
• After soldering, do not deal with the product before its ter	mperature drop dow	n to room temperature	`
3.	inperature drop dow	n to room temperature	
Cleaning			
	30	3	50
30		LED	
It is recommended that alcohol Anhydrous ethanol b	e used as a solvent	for cleaning after sold	ering.
Cleaning is to go under 30 for 3 minutes or 50 for 30) seconds. When usi	ng other solvents, it sl	nould be
confirmed beforehand whether the solvents will dissolve	the package and the	resin or not.	
	300W	LED	
LED			
Ultrasonic cleaning is also an effective way for cleaning.		0	-
on factors such as ultrasonic power. Generally, the ultraso	-	C	
it will cause LED damage. Before cleaning, a pre-test sh	hould be done to com	nfirm if any damage t	o LEDs will
occur.			
DOD			
PCB		1	PCB
Note: This general guideline may not apply to all PCB designs and com in practice is influenced by many factors, it should be spe	-		-
of the soldering equipment.	echanizeu base on ti	The FCB designs and con	ningurations

V	HI GUANGDONG SHENLITE TECHNOLOGY, INC.
M 0.0011	(1)
	itions (1)
1.	
	Storage
•	Moisture proof, anti-electrostatic package and moisture absorbent material are used, to keep moisture to
	minimum. Humidity indicator card inside to test if the products are moisted.
•	<30 <60 RH 2
	Storage environment: Before opening the package, the product should be kept at 30 or less and humidit
	less than 60% RH, When the storage time more than 2 months, need to be used to bake.
•	
	Before using, please check whether there is any air leakage or not, If the bag has leaked air, Please bake the
	product with below condition.
•	<30 <60 RH 12h
	Before soldering the product must be stored under the condition of <30 and <60 RH. Under the conditions the SMD LEDs must be used (subject to reflow oven) within 12 hours.
•	$70\pm5 \times 24h$
	Baking conditions: $70\pm5 \times 24h$.
2.	
	Static Electricity
•	
	Static electricity or surge voltage damages the LEDs. Damaged LEDs will show some unusual characteristic
	such as the forward voltage becomes lower, or the LEDs can not be lighted up. In view of the above, we shou
	do some anti-static precautions when using the SMD LEDs.
•	
	All devices, equipments and machineries must be properly grounded, at the same time we should tal measures to prevent anti-static and voltage surge.
•	mensares to provent unit suure une voluige surge.
	It is also recommended that anti-electrostatic wrist bands, pads, uniforms, gloves or containers can be used
	when dealing with the LEDs.





Precautions (2)

LIGH

3.

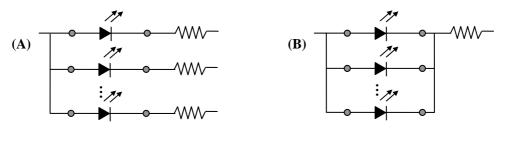
Design Consideration

LED

In designing a circuit, the current through each LED must not exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change which will probably lead to damage.

А			LED	В	
	LED	VF			LED

It is recommended to use Circuit A which regulates the current flowing through each LED rather than Circuit B. When driving LEDs with a constant voltage in Circuit B, the current through the LEDs may vary due to the variation in Forward Voltage (VF) of the LEDs. In the worst case, some LED may be subjected to stress in the excess of the Absolute Maximum Rating.



• LED

LED

Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decrease, Color change and so on. Please consider the heat dissipation when making the system design.

4.
Reverse voltage protection
LED
LED
LED
LED
LED
SV
In general, the reverse current of LED is very small, which won't affect the normal use of components. But when it is often suffered the reverse voltage which exceeds the limit of the component then it will be damaged.

Part No./	SL-T3510RGBA-L120	Page	12 of 13
		0	



Precautions (3)

LIGHT

Such as the reverse current increase rapidly. And it will cause the string light when the screen is black. So please pay attention to controlling the reverse voltage which less than 5V is recommended.

5.

The safe temperature for LEDs working

LED

75

The high temperature will make the LEDs' Luminous Intensity decreased radically, if LEDs are used in hot environment for a long time, they will be disabled easily. When LEDs are used in a high density array, we suggest that the LEDs' surface temperature should be lower than 55 and the legs' temperature should be lower than 75 .

55

6.

Others

When handling the product, touching the encapsulation with bare hands will not only contaminate its surface, but also have an effect on its optical characteristics. Excessive force to the encapsulation might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



• LED

The epoxy resin of encapsulation is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not hold by the epoxy resin, be careful.

Part No./ SL-15510KGBA-L120 Page 15 01 15	Part No./	SL-T3510RGBA-L120	Page	13 of 13
---	-----------	-------------------	------	----------